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11. A semiconductor fabrication method, comprising the steps of:  
forming surface features simultaneously with the formation of alignment marks on a wafer;  
forming a first conducting layer over said surface features;  
forming an insulating layer on said first conducting layer;  
forming a second conducting layer on said insulating layer to thereby form a capacitor structure;  
wherein said capacitor structure is not planar.

13. The circuit structure of Claim 11, wherein said first and said second conducting layers are polysilicon.

14. The circuit structure of Claim 11, wherein said features are formed by patterning and etching.

15. A semiconductor fabrication method, comprising the steps of:  
forming a sacrificial layer of oxide on selected areas of a substrate;  
stripping said sacrificial layer to form recesses in said substrate;  
forming a first insulating layer on said substrate over said recesses;  
5 forming a first conducting layer on said first insulating layer;  
forming a second insulating layer on said first conducting layer;  
forming a second conducting layer on said second insulating layer  
to thereby form a capacitor structure;  
wherein said capacitor structure has non-planar surface features.

16. The circuit structure of Claim 15, wherein said second insulating layer is SiO<sub>2</sub>.

17. The circuit structure of Claim 15, wherein said first and second conducting layers are polysilicon.

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